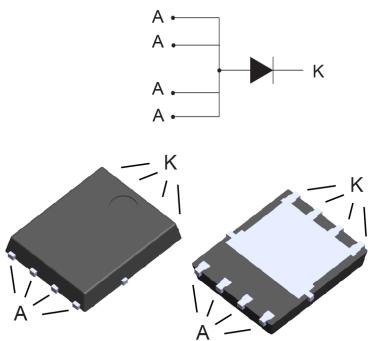


## 170 V, 30 A power Schottky rectifier



PowerFLAT™ 5x6  
(non-contractual)

### Features

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward voltage drop
- Low thermal resistance
- High avalanche capability specified
- ECOPACK®2 compliant

### Applications

- Switching diode
- SMPS
- DC/DC converter
- Telecom power

### Description

This Schottky rectifier is ideally suited for switch mode power supply and high frequency DC to DC converters.

Packaged in PowerFLAT™ 5x6, the **STPS30170DJF** is optimized for use in low voltage high frequency inverters, free-wheeling and polarity protection applications.

Its low profile was especially designed to be used in applications with space-saving constraints.

PowerFLAT™ is a trademark of STMicroelectronics.

Product status	
STPS30170DJF	
Product summary	
I <sub>F(AV)</sub>	30 A
V <sub>RRM</sub>	170 V
T <sub>j(max.)</sub>	150 °C
V <sub>F(typ.)</sub>	0.71 V

## 1 Characteristics

**Table 1. Absolute Ratings (limiting values at 25 °C, unless otherwise specified, anode terminals short circuited)**

Symbol	Parameter		Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage		170	V	
I <sub>F(RMS)</sub>	Forward rms current		45	A	
I <sub>F(AV)</sub>	Average forward current, $\delta = 0.5$ , square wave		30	A	
I <sub>FSM</sub>	Surge non repetitive forward current		t <sub>p</sub> = 10 ms sinusoidal	200	A
P <sub>ARM</sub>	Repetitive peak avalanche power		t <sub>p</sub> = 10 µs, T <sub>j</sub> = 125 °C	900	W
T <sub>stg</sub>	Storage temperature range		-65 to +175	°C	
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup>		150	°C	

1.  $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$  condition to avoid thermal runaway for a diode on its own heatsink.

**Table 2. Thermal resistance parameters**

Symbol	Parameter	Max. value	Unit
R <sub>th(j-c)</sub>	Junction to case	2.5	°C/W

For more information, please refer to the following application note :

- AN5046 : Printed circuit board assembly recommendations for STMicroelectronics PowerFLAT™ packages

**Table 3. Static electrical characteristics (anode terminals short circuited)**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-		15	µA
		T <sub>j</sub> = 125 °C		-	4	12	mA
V <sub>F</sub> <sup>(2)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 15 A	-		0.88	V
		T <sub>j</sub> = 125 °C		-	0.65	0.70	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 30 A			0.95	
		T <sub>j</sub> = 125 °C			0.71	0.79	

1. Pulse test: t<sub>p</sub> = 5 ms, δ < 2%

2. Pulse test: t<sub>p</sub> = 380 µs, δ < 2%

To evaluate the conduction losses use the following equation:

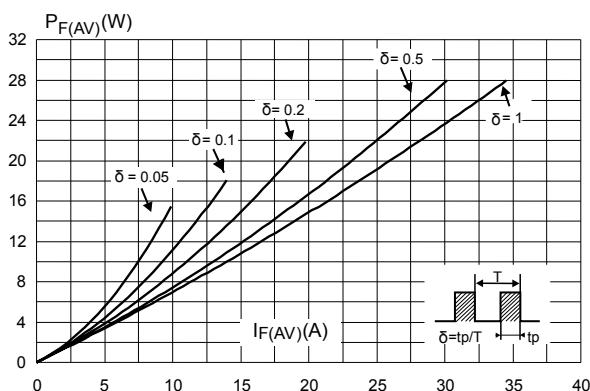
$$P = 0.65 \times I_{F(AV)} + 0.0046 I_F^2 \text{ (RMS)}$$

For more information, please refer to the following application notes related to the power losses :

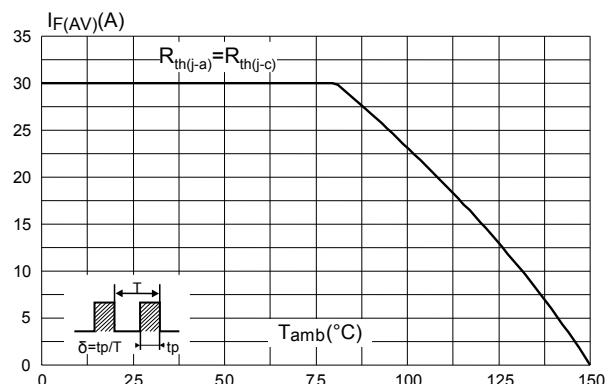
- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

## 1.1 Characteristics (curves)

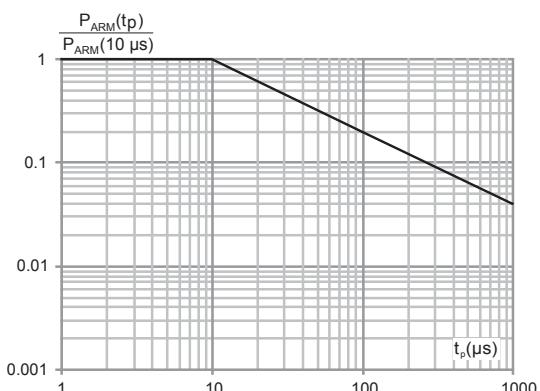
**Figure 1. Average forward power dissipation versus average forward current**



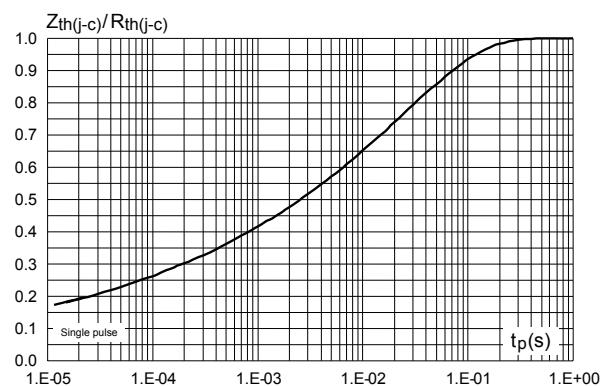
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )**



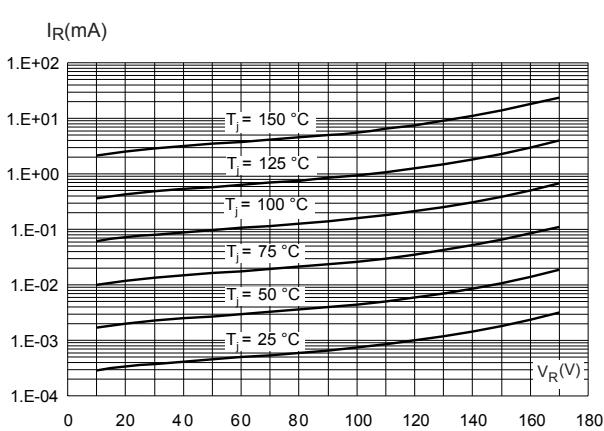
**Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j = 125^\circ C$ )**



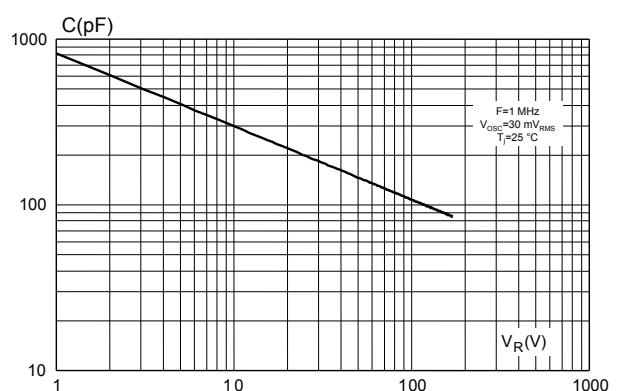
**Figure 4. Relative variation of thermal impedance junction to case versus pulse duration**

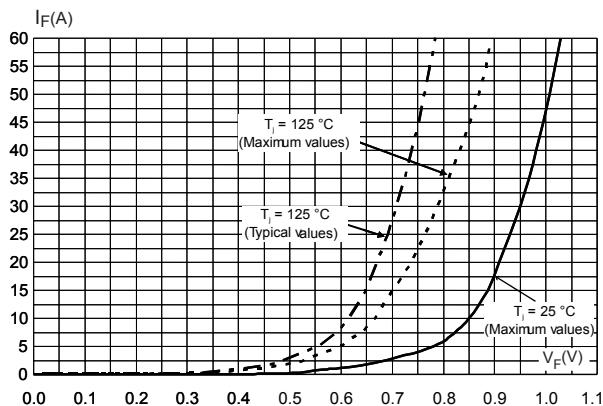
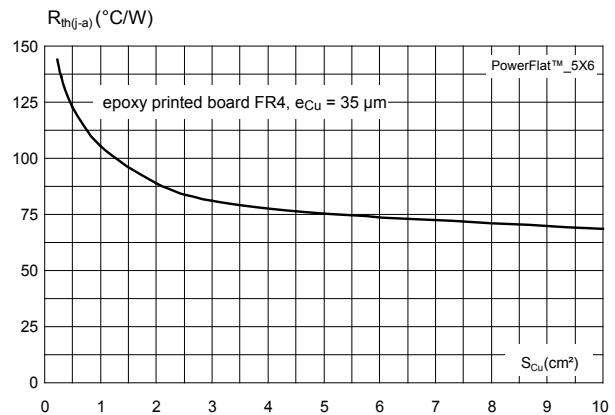


**Figure 5. Reverse leakage current versus reverse voltage applied (typical values)**



**Figure 6. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 7. Forward voltage drop versus forward current****Figure 8. Thermal resistance junction to ambient versus copper surface under tab**

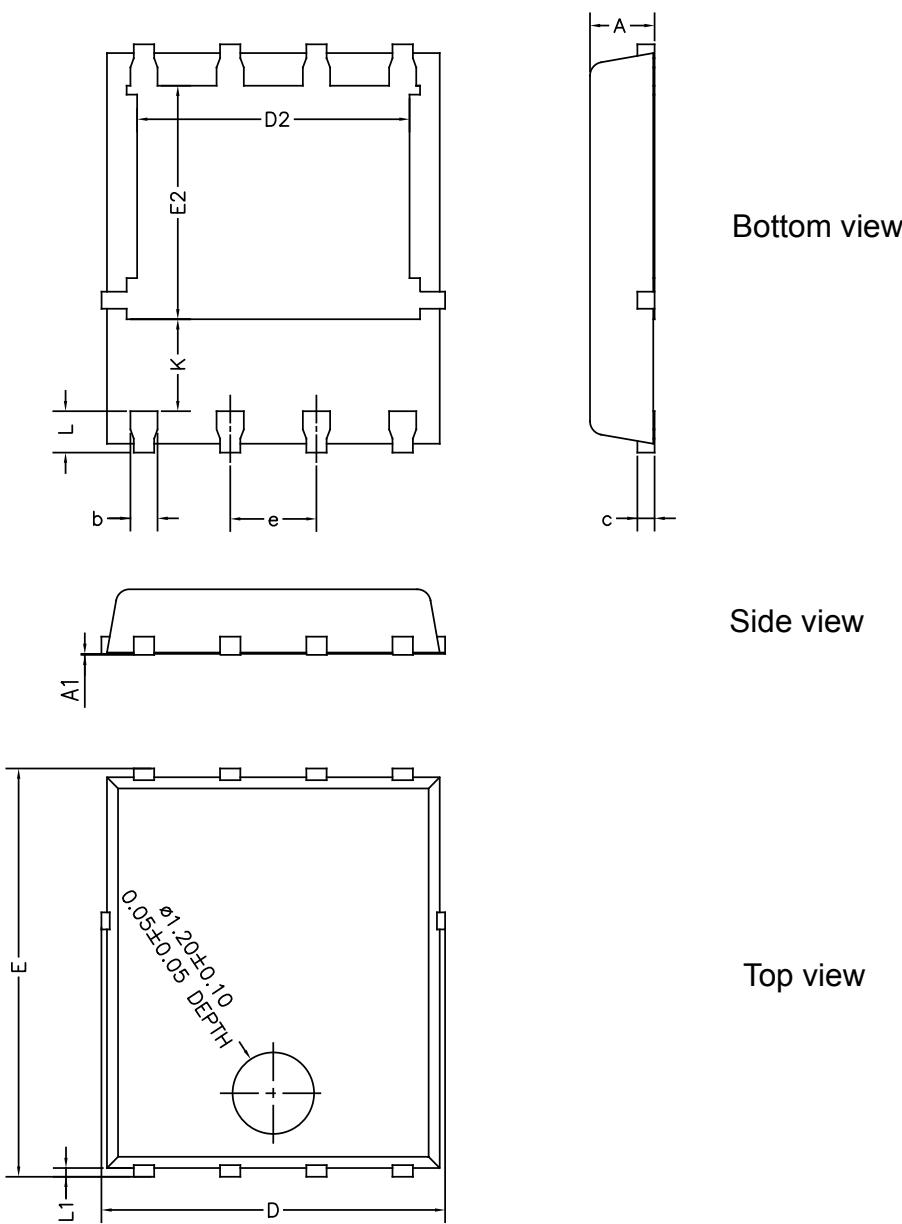
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 PowerFLAT™ 5x6 package information

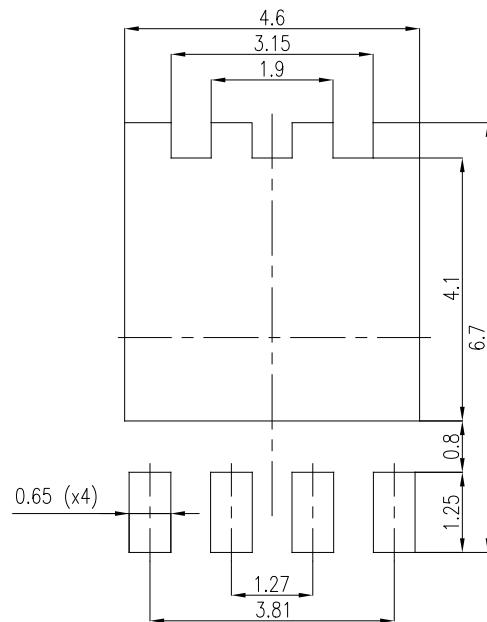
- Epoxy meets UL 94,V0
- Cooling method: by conduction (C)

Figure 9. PowerFLAT™ 5x6 package outline (non-contractual)



**Table 4. PowerFLAT™ 5x6 mechanical data**

Ref	Dimensions			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	0.80		1.00	0.031		0.039
A1	0.00		0.05	0.000		0.002
b	0.30		0.50	0.01		0.02
c		0.25			0.010	
D	4.80		5.40	0.189		0.212
D2	3.91		4.45	0.154		0.175
e		1.27			0.050	
E	5.90		6.35	0.232		0.250
E2	3.34		3.70	0.138		0.146
L	0.50		0.80	0.020		0.031
K	1.10		1.575	0.015		0.023
L1	0.05	0.15	0.25	0.002	0.006	0.009

**Figure 10. PowerFLAT™ 5x6 recommended footprint (dimensions are in mm)**

**3****Ordering information**

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**Table 5. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS30170DJF-TR	PS30 170	PowerFLAT 5x6	0.095 g	3000	Tape and reel

## Revision history

**Table 6. Document revision history**

Date	Revision	Changes
06-Nov-2009	1	First issue.
30-Jul-2010	2	Updated Table 1.
20-May-2011	3	Corrected order code and marking in Table 6.
05-Jun-2018	4	Updated Table 1. Absolute Ratings (limiting values at 25 °C, unless otherwise specified, anode terminals short circuited) and Figure 3. Normalized avalanche power derating versus pulse duration ( $T_j = 125$ °C). Minor text changes to improve readability.
08-Feb-2019	5	Updated Section Cover image, Figure 9. PowerFLAT™ 5x6 package outline (non-contractual) and Table 4. PowerFLAT™ 5x6 mechanical data.

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